

MBD701, MMBD701L, SMMBD701L

Preferred Device

Silicon Hot-Carrier Diodes Schottky Barrier Diodes

These devices are designed primarily for high-efficiency UHF and VHF detector applications. They are readily adaptable to many other fast switching RF and digital applications. They are supplied in an inexpensive plastic package for low-cost, high-volume consumer and industrial/commercial requirements. They are also available in a Surface Mount package.

Features

- Extremely Low Minority Carrier Lifetime – 15 ps (Typ)
- Very Low Capacitance – 1.0 pF @ $V_R = 20$ V
- High Reverse Voltage – to 70 V
- Low Reverse Leakage – 200 nA (Max)
- AEC Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- Pb-Free Packages are Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V_R	70	V
Forward Power Dissipation @ $T_A = 25^\circ\text{C}$ MBD701 MMBD701L, SMMBD701L	P_F	280 200	mW
Derate above 25°C MBD701 MMBD701L, SMMBD701L		2.8 2.0	mW/ $^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to +125	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to +150	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

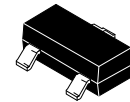


ON Semiconductor®

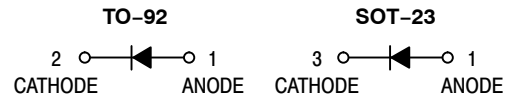
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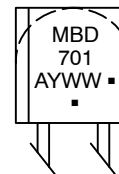
TO-92 2-Lead
CASE 182
STYLE 1



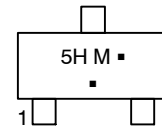
SOT-23 (TO-236)
CASE 318
STYLE 8



MARKING DIAGRAMS



TO-92



SOT-23

- A = Assembly Location
- Y = Year
- WW = Work Week
- 5H = Device Code (SOT-23)
- M = Date Code*
- = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MBD701, MMBD701L, SMMBD701L

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage (I _R = 10 μAdc)	V _{(BR)R}	70	-	-	V
Total Capacitance (V _R = 20 V, f = 1.0 MHz) Figure 1	C _T	-	0.5	1.0	pF
Reverse Leakage (V _R = 35 V) Figure 3	I _R	-	9.0	200	nAdc
Forward Voltage (I _F = 1.0 mAdc) Figure 4	V _F	-	0.42	0.5	Vdc
Forward Voltage (I _F = 10 mAdc) Figure 4	V _F	-	0.7	1.0	Vdc

ORDERING INFORMATION

Device	Package	Shipping [†]
MBD701	TO-92	1,000 Units / Bulk
MBD701G	TO-92 (Pb-Free)	1,000 Units / Bulk
MMBD701LT1	SOT-23	3,000 / Tape & Reel
MMBD701LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SMMBD701LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBD701LT3	SOT-23	10,000 / Tape & Reel
MMBD701LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TYPICAL ELECTRICAL CHARACTERISTICS

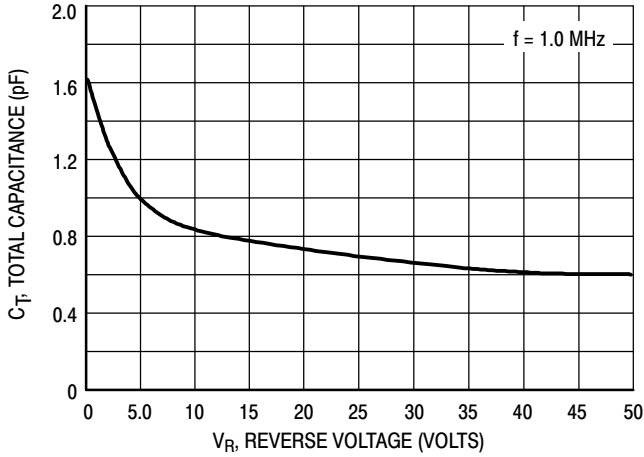


Figure 1. Total Capacitance

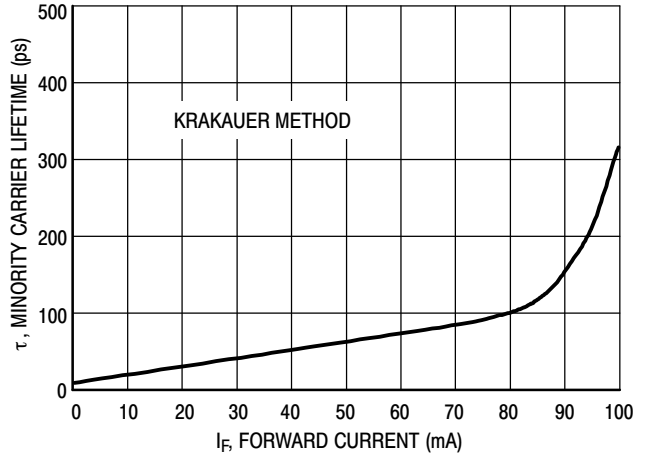


Figure 2. Minority Carrier Lifetime

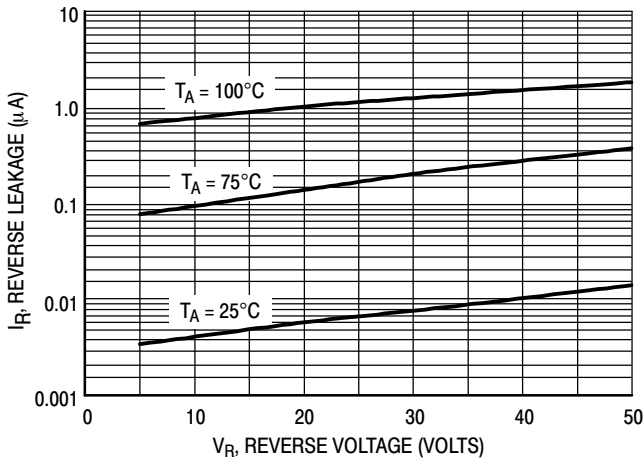


Figure 3. Reverse Leakage

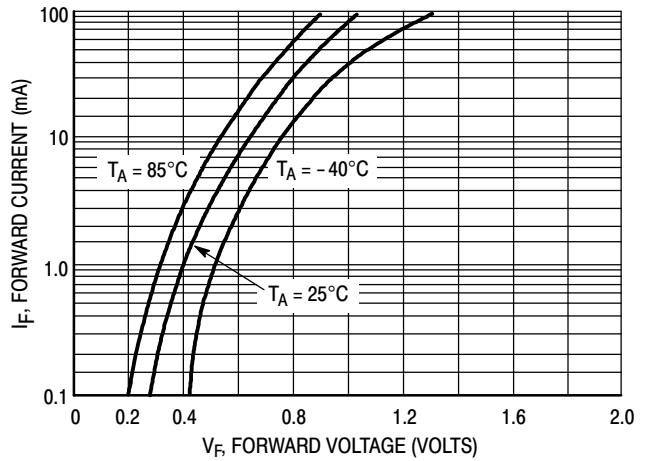


Figure 4. Forward Voltage

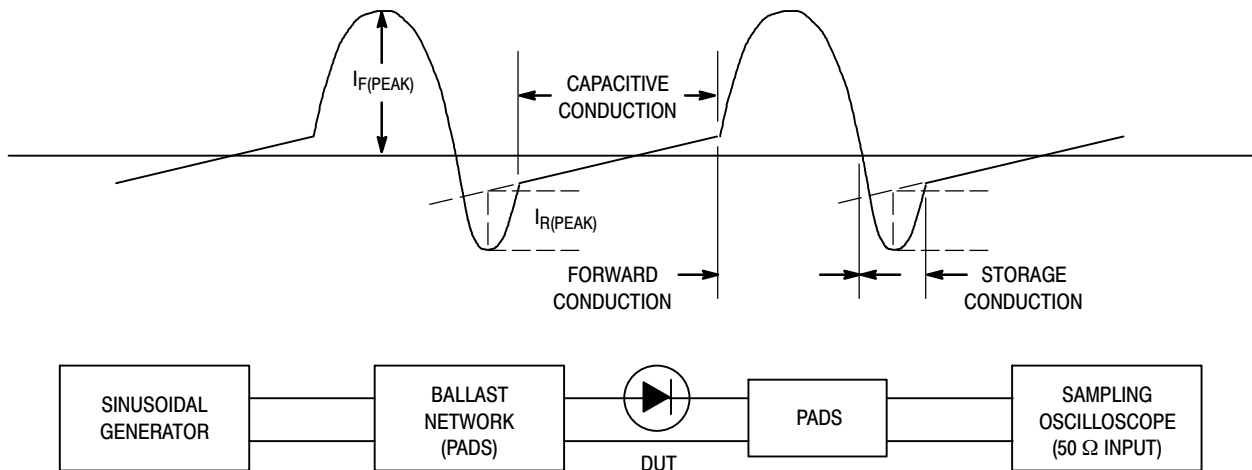
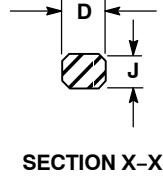
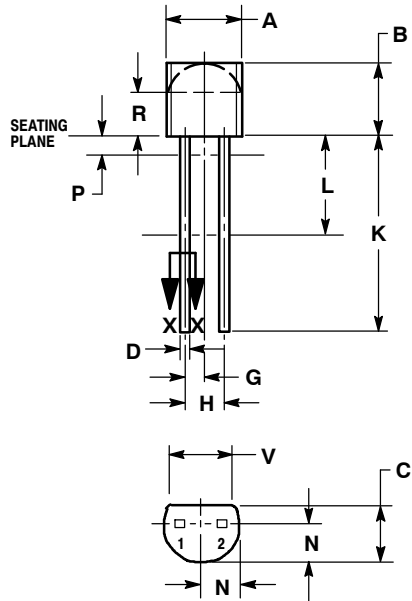


Figure 5. Krakauer Method of Measuring Lifetime

MBD701, MMBD701L, SMMBD701L

PACKAGE DIMENSIONS

TO-92 (TO-226AC)
CASE 182-06
ISSUE L



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND ZONE R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.21
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.050 BSC		1.27 BSC	
H	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.41
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.03	2.66
P	---	0.050	---	1.27
R	0.115	---	2.93	---
V	0.135	---	3.43	---

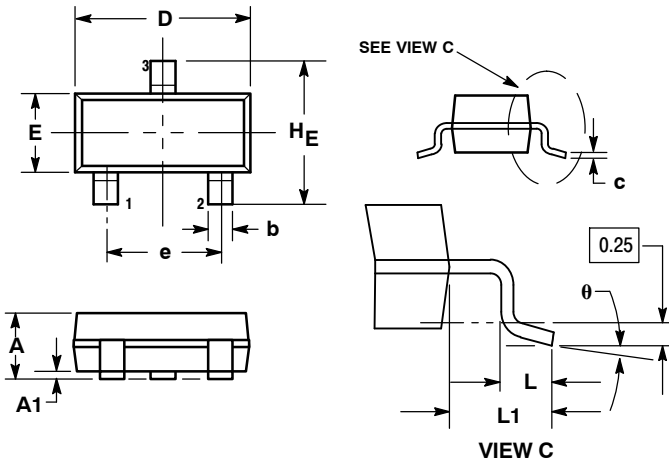
STYLE 1:

- PIN 1. ANODE
2. CATHODE

MBD701, MMBD701L, SMMBD701L

PACKAGE DIMENSIONS

SOT-23 (TO-236)
CASE 318-08
ISSUE AP



NOTES:

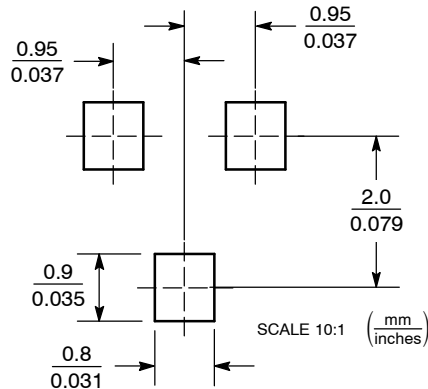
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

STYLE 8:

1. ANODE
2. NO CONNECTION
3. CATHODE

SOLDERING FOOTPRINT



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